

ABSTRACT OF THE DISCLOSURE

A thermal treatment apparatus comprises a heating device for heating a thermal treatment chamber, and a gas supplying device for supplying atmospheric gas to the thermal treatment chamber. A temperature measuring device measures temperature in the thermal treatment chamber, and a time measuring device measures a heat treatment time during which the heating device heats the thermal treatment chamber. A control device controls the heating conditions provided by the heating device and atmospheric gas supply conditions provided by the gas supplying device in coordinated relation to each other based on the temperature in the thermal treatment chamber measured by the temperature measuring device and the heat treatment time measured by the time measuring device. The thermal treatment chamber can therefore be controlled more accurately. The invention also pertains to a method for using the above-described thermal treatment apparatus.

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